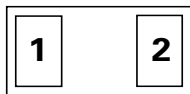


AQ0115-01ETG**1 V Bidirectional Discrete TVS in SOD882, General Purpose ESD Protection****Pinout****Functional Block Diagram****Description**

The AQ0115-01ETG features low breakdown/turn on voltages, making them more ideal protectors of low voltage -1.0 to +1.0 V data lines. These robust diodes can safely absorb repetitive ESD strikes above the maximum level specified in IEC 61000-4-2 international standard (Level 4, ± 8 kV contact discharge) without performance degradation.

Features

- ESD, IEC 61000-4-2, ± 30 kV contact/air
- ESD, ISO 10605, 330 pF 330 Ω , ± 30 kV contact/air
- EFT, IEC 61000-4-4, 40 A (5/50 ns)
- Maximum surge tolerance, IEC 61000-4-5, 2nd edition, 12 A (8/20 μ s)
- Halogen-free, lead-free and RoHS compliant
- Moisture sensitivity level (MSL-1)
- AEC-Q101 qualified and PPAP capable

Applications

- Automotive
- Low voltage GPIO for MCU
- Industry
- Medical

AQ0115-01ETG**1 V Bidirectional Discrete TVS in SOD882, General Purpose ESD Protection****Absolute Maximum Ratings**

Symbol	Parameter	Value	Units
I_{PP}	Peak Current ($t_p = 8/20 \mu s$)	12	A
T_{OP}	Operating Temperature	-40 to 150	°C
T_{STOR}	Storage Temperature	-55 to 150	°C

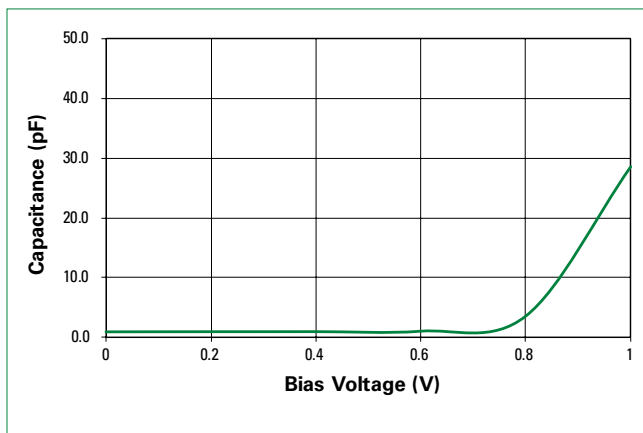
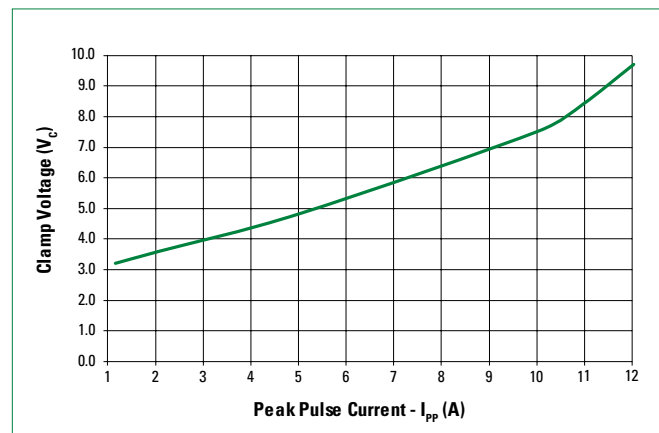
Caution: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Electrical Characteristics ($T_{OP} = 25^\circ C$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V_{RWM}				1.0	V
Breakdown Voltage	V_{BR}	$I_R = 1 \text{ mA}$	1.4	1.6		V
Reverse Leakage Current	I_{LEAK}	$V_R = 1 \text{ V}$			1	μA
Clamp Voltage ¹	V_C	$I_{PP} = 1 \text{ A}$, $t_p = 8/20 \mu s$, I/O to GND		3.0		V
		$I_{PP} = 12 \text{ A}$, $t_p = 8/20 \mu s$, I/O to GND		9.7		V
Dynamic Resistance ²	R_{DYN}	TLP, $t_p = 100 \text{ ns}$, I/O to GND		0.3		Ω
ESD Withstand Voltage ^{1,3,4}	V_{ESD}	IEC 61000-4-2 (Contact Discharge)	± 30			kV
		IEC 61000-4-2 (Air Discharge)	± 30			kV
		ISO10605 (Contact Discharge)	± 30			kV
		ISO10605 (Air Discharge)	± 30			kV
Diode Capacitance ¹	C_{IO-GND}	Reverse Bias = 0 V, $f = 1 \text{ MHz}$, I/O to GND		1.0		pF

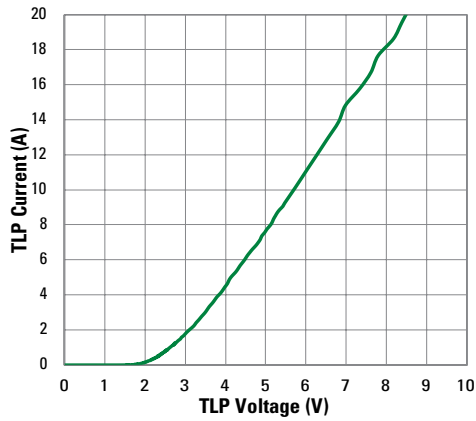
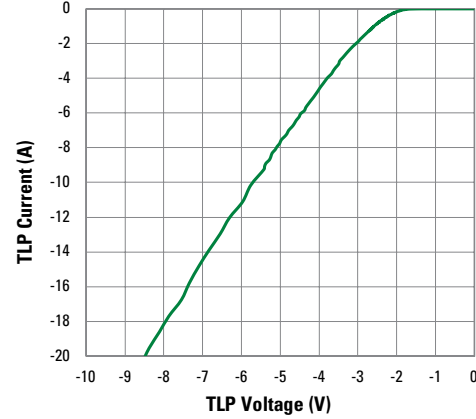
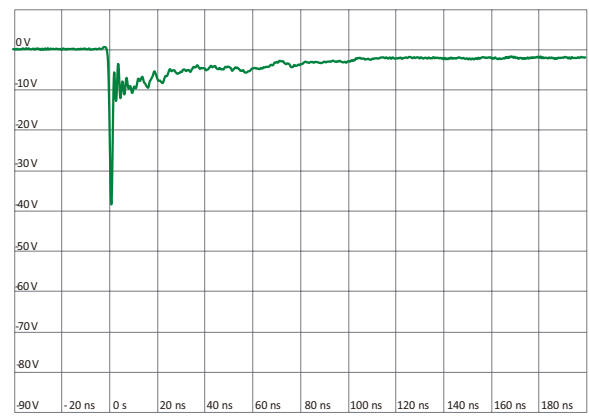
Note:

- Parameter is guaranteed by design and/or component characterization.
- Transmission Line Pulse (TLP) with 100ns width, 0.2 ns rise time, and average window $t_1 = 70 \text{ ns}$ to $t_2 = 90 \text{ ns}$
- Device stressed with ten non-repetitive ESD pulses according to IEC61000-4-2 ($R = 330 \Omega$, $C = 150 \text{ pF}$).
- Device stressed with three non-repetitive ESD pulses according to ISO10605 ($R = 330 \Omega$, $C = 330 \text{ pF}$).

Capacitance vs. Reverse Bias**Clamping Voltage vs IPP**

AQ0115-01ETG

1 V Bidirectional Discrete TVS in SOD882, General Purpose ESD Protection

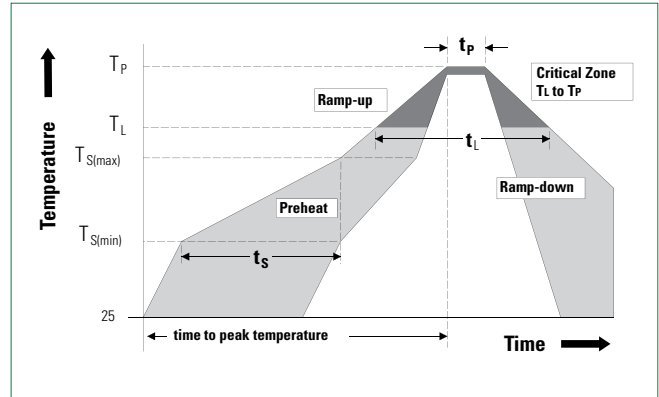
Positive Transmission Line Pulsing (TLP) Plot**Negative Transmission Line Pulsing (TLP) Plot****IEC 61000-4-2 +8 kV Contact ESD Clamping Voltage****IEC 61000-4-2 -8 kV Contact ESD Clamping Voltage****ISO10605 Contact Discharge Plot at +8 kV****ISO10605 Contact Discharge Plot at -8 kV**

AQ0115-01ETG

1 V Bidirectional Discrete TVS in SOD882, General Purpose ESD Protection

Soldering Parameters

Reflow Condition		Pb – free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150 °C
	- Temperature Max ($T_{s(max)}$)	200 °C
	- Time (min to max) (t_s)	60 – 120 seconds
Average Ramp Up Rate (Liquidus) Temp (T_L) to Peak		3 °C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/second max
Reflow	- Temperature (T_L) (Liquidus)	217 °C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time Within 5 °C of Actual Peak Temperature (t_p)		30 seconds
Ramp-down Rate		6 °C/second max
Time 25 °C to Peak Temperature (T_p)		8 minutes max
Do Not Exceed		260 °C



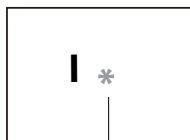
Ordering Information

Part Number	Package	Min. Order Qty.
AQ0115-01ETG	SOD882	10000

Product Characteristics

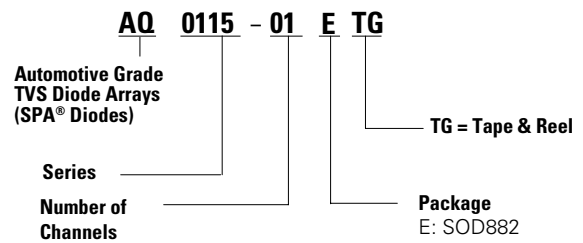
Lead Plating	Matte tin
Lead Material	Copper alloy
Body Material	Molded compound
Flammability	UL recognized compound meeting flammability rating V-0

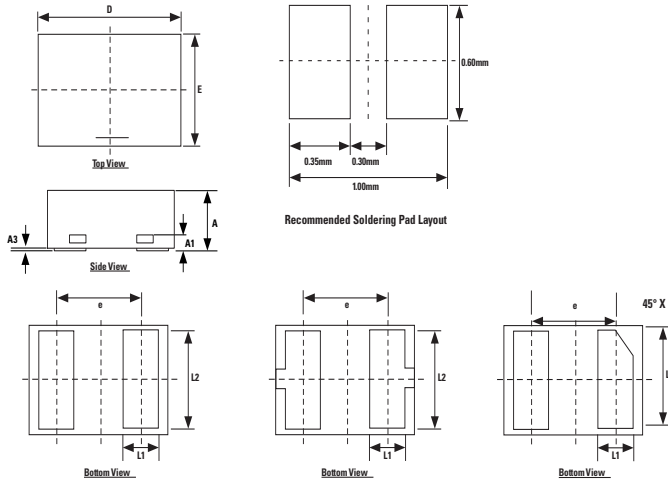
Part Marking System



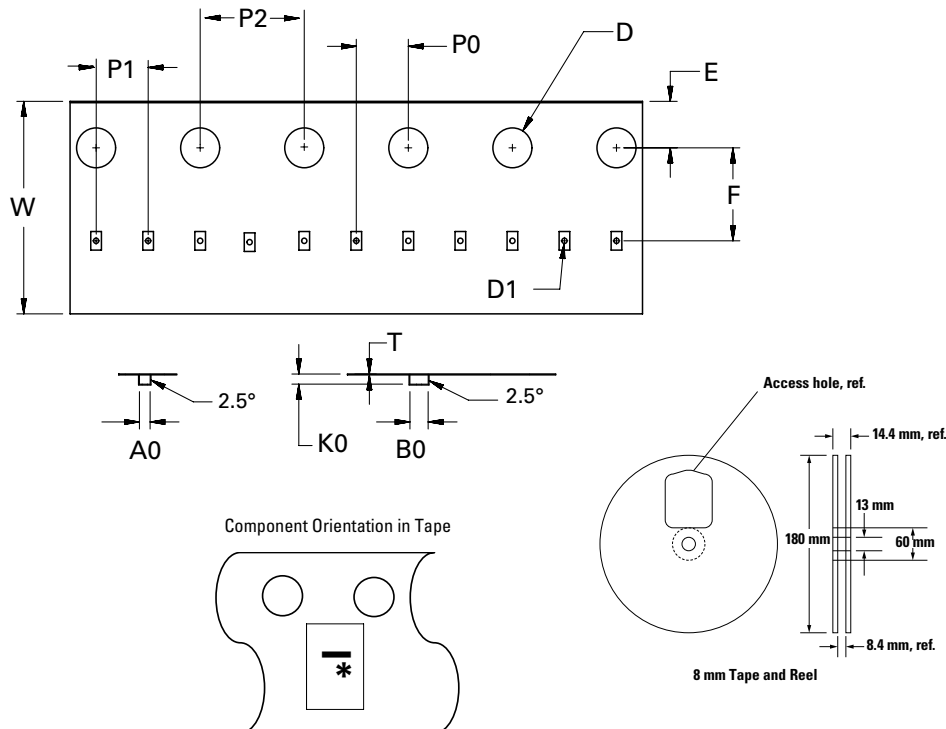
I : Part Code
* : Date Code

Part Numbering System



AQ0115-01ETG**1 V Bidirectional Discrete TVS in SOD882, General Purpose ESD Protection****Package Dimensions — SOD882**

Symbol	DIMENSIONS (mm)		
	Min.	Nor.	Max.
A	0.36	0.45	0.55
A1	0.125/0.150 (REF)		
A3	0.00	0.02	0.05
L1	0.20	0.25	0.30
L2	0.45	0.50	0.55
D	0.93	1.00	1.07
E	0.53	0.60	0.67
e	0.65 BSC		
h	0.07	0.12	0.17

Embossed Carrier Tape & Reel Specification — SOD882

Symbol	Millimeters
A0	0.70+/-0.05
B0	1.15+/-0.05
D	1.50+0.10
D1	0.40+/-0.10
E	1.75+/-0.10
F	3.50+/-0.05
K0	0.55+/-0.05
P0	2.00+/-0.05
P1	2.00+/-0.10
P2	4.00+/-0.10
T	0.20+/-0.03
W	8.00+0.30/-0.10

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